

43rd Annual NDIA Fuze Conference

8 April 1999

Miniature Electronic Safing and Arming Device

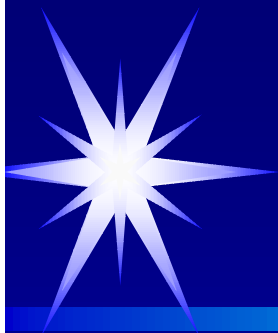
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Sandia is a multiprogram laboratory operated by Sandia Corporation, a Lockheed Martin Company,
for the United States Department of Energy under contract DE-AC04-94AL85000.





Development Team & Contributors

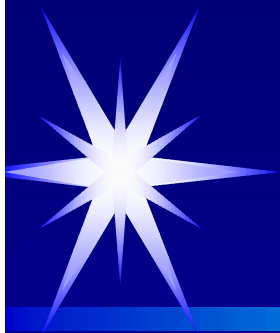
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Eddie Hoover
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DOD Labs





The Challenge



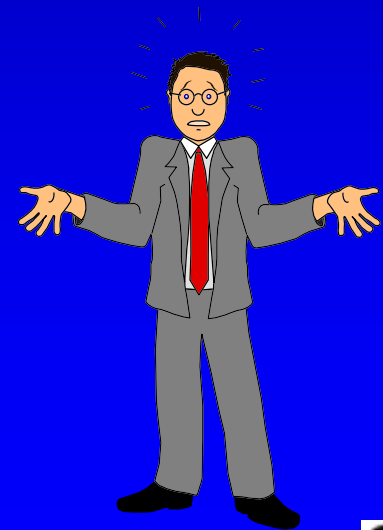
- Develop a miniature, low cost, all electronic safing and arming device.
- Provide direction for future technology improvements and developments





Why an ESAD?

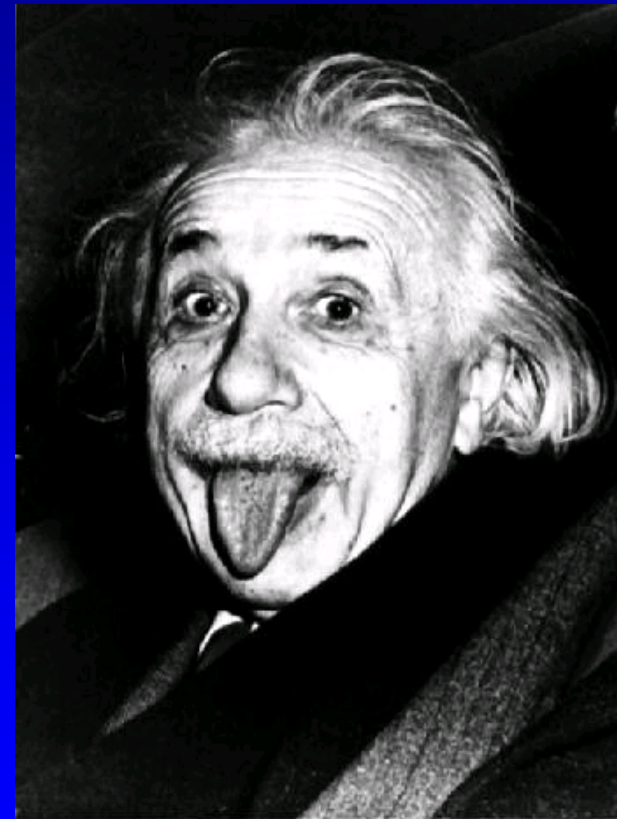
- No primary explosives
- No moving parts
- Long stockpile storage life
- Increased testability
- Adaptable to operating in harsh environments

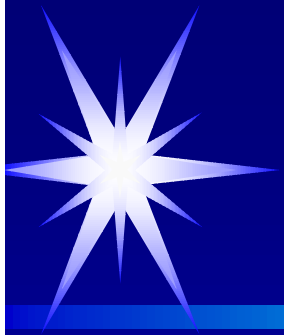




Why an ESAD (Cont.)

- Additional intelligence can be incorporated into the design which can include target detection, fuzing logic, and mission specific programmability





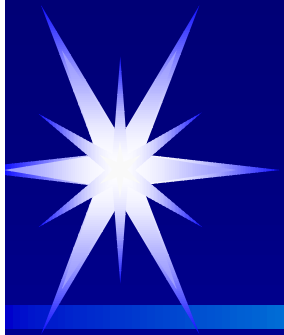
DEFINING THE GOALS

- ✦ Initial design goals were based on artillery fuze applications



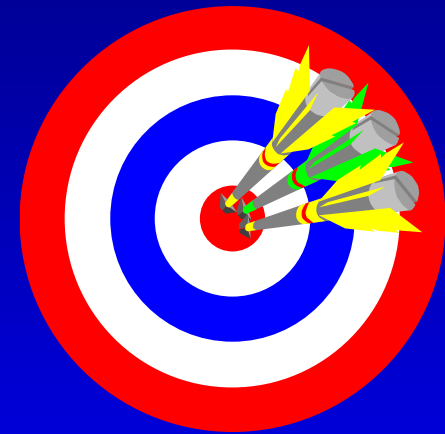
- ✦ Future design goals will include mortar, and tank fuze applications

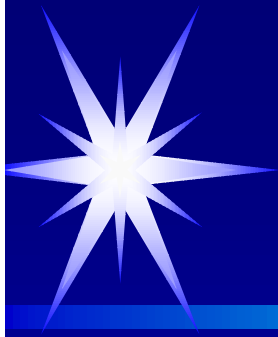




SYSTEM DESIGN GOALS

- * Minimize Volume
- * Minimize Cost
- * Address Manufacturability
- * Define Technology Improvements Needed
- * Define New Technologies Needed



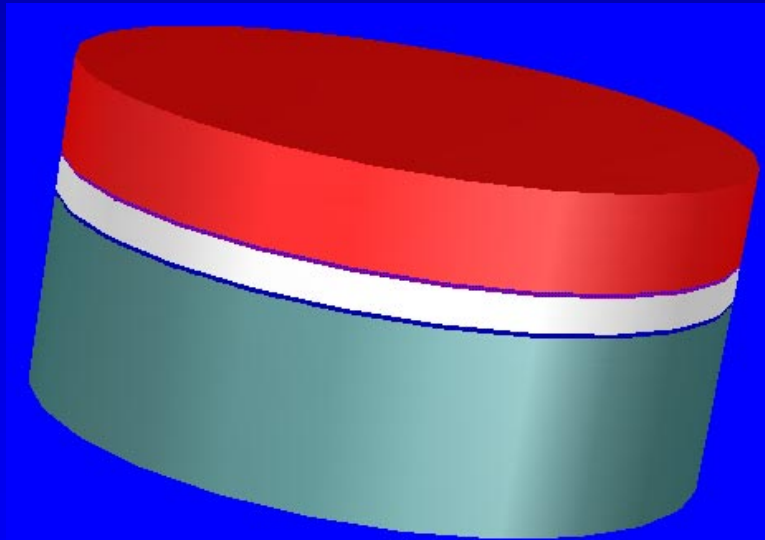


ENABLING TECHNOLOGIES

- Low energy detonators
- Solid state high voltage switch
- High voltage ceramic capacitors
- Miniaturization of electronic components with increased functionality (pocket electronics)

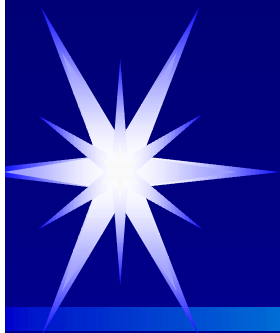


VOLUME GOALS



- ★ FY96 - 3.77 in³
 - Original goal
- ★ FY97 - 1.25 in³
 - Achieved in hardware
- ★ FY98 - 0.85 in³
 - Achieved Analytically
- ★ FY99 - 0.75 in³
 - Progressing

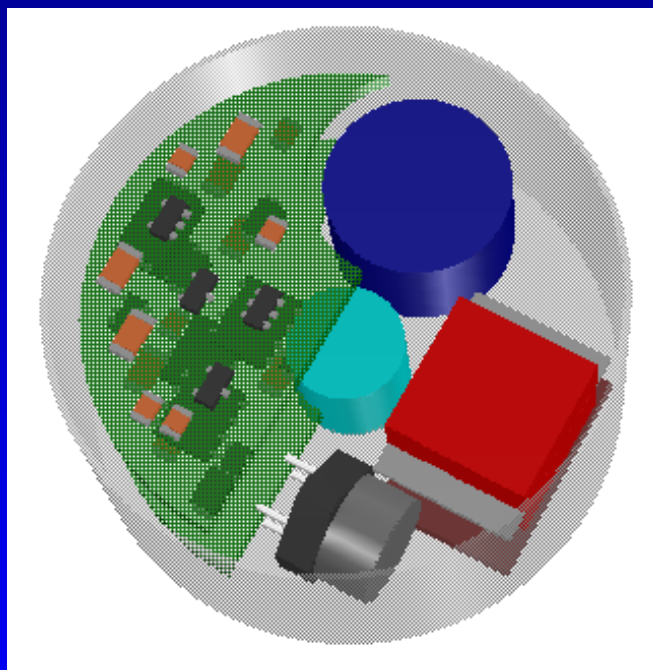




FY97 MINIATURE ESAD

CONTENTS:

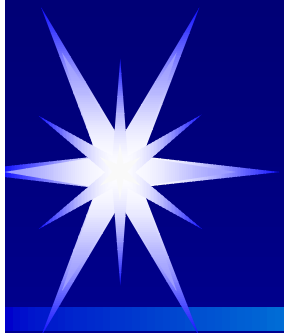
Setback Activated Battery
Safety Logic
Acceleration Sensor
HV Drive Circuitry
HV Converter
Solid State HV Switch
HV Switch Gate Drive
Detonator
HNS Pellet



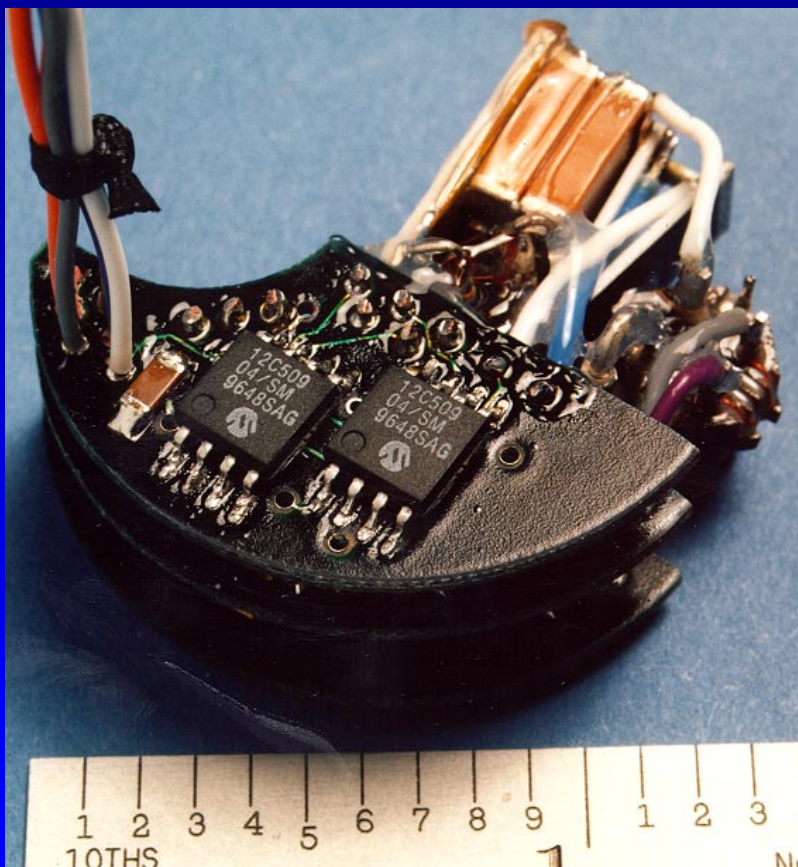
1.5 inch diameter
0.7 inch high

1.25 Cubic Inches



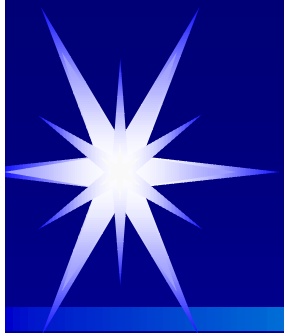


FY97 ESAD (TOP)



The FY97 miniaturized design is functional and successfully fires Standard Navy Chip Detonators with HNS IV pellets





FY97 ESAD (SIDE)

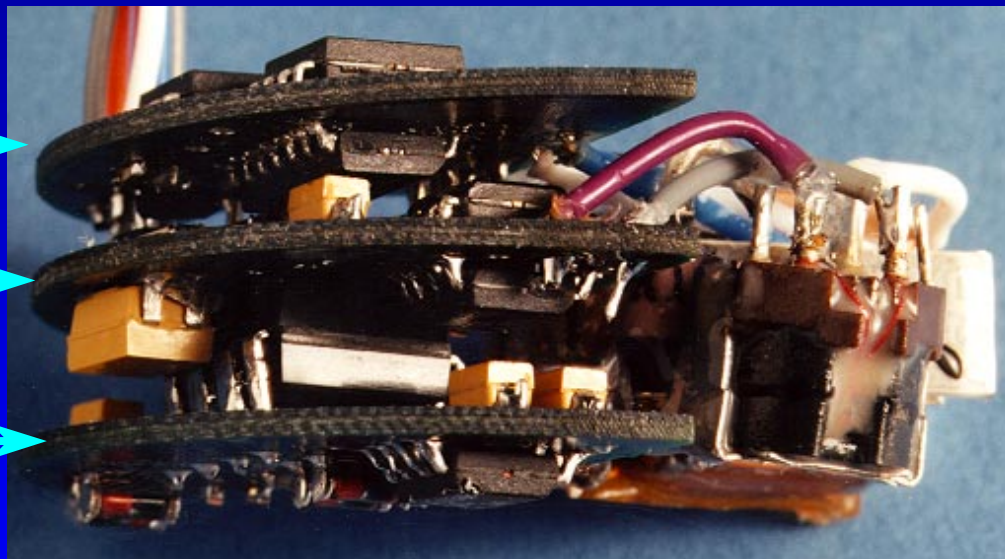
Safety Logic

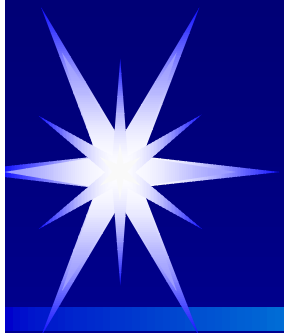


HV Converter Drive



MCT Gate Drive
(Deleted in FY98)





FY97 ESAD (BOTTOM)

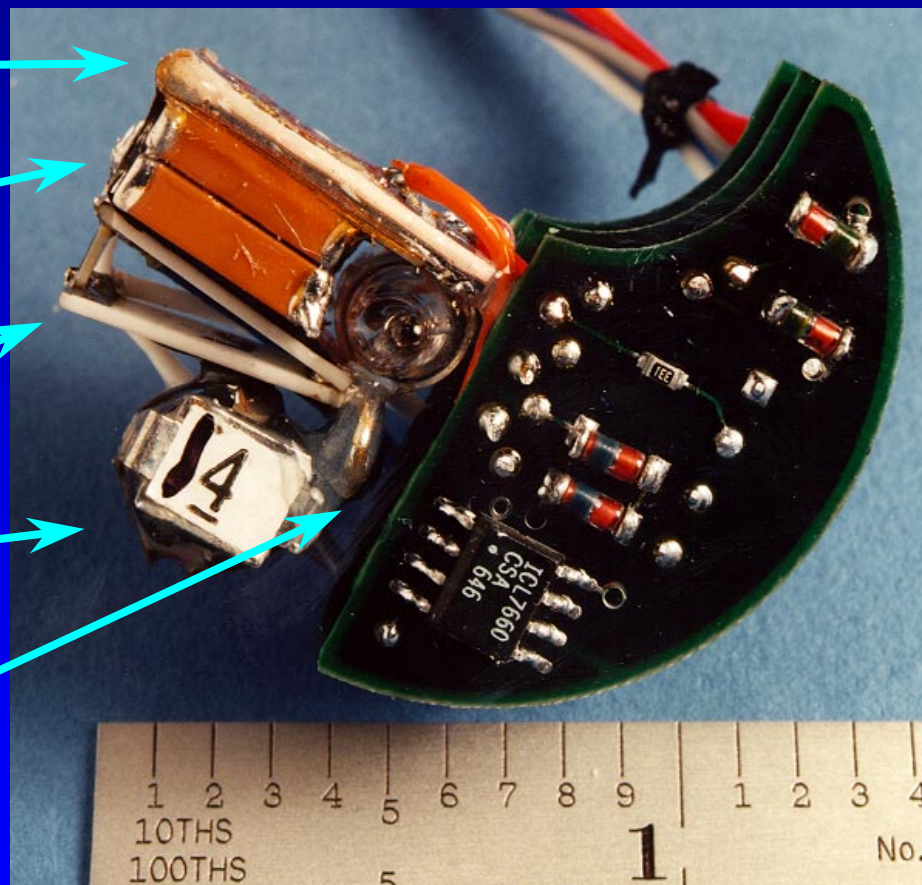
HV MCT Switch

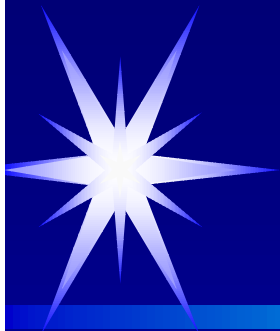
2 HV Capacitors

HV Bleed Resistors

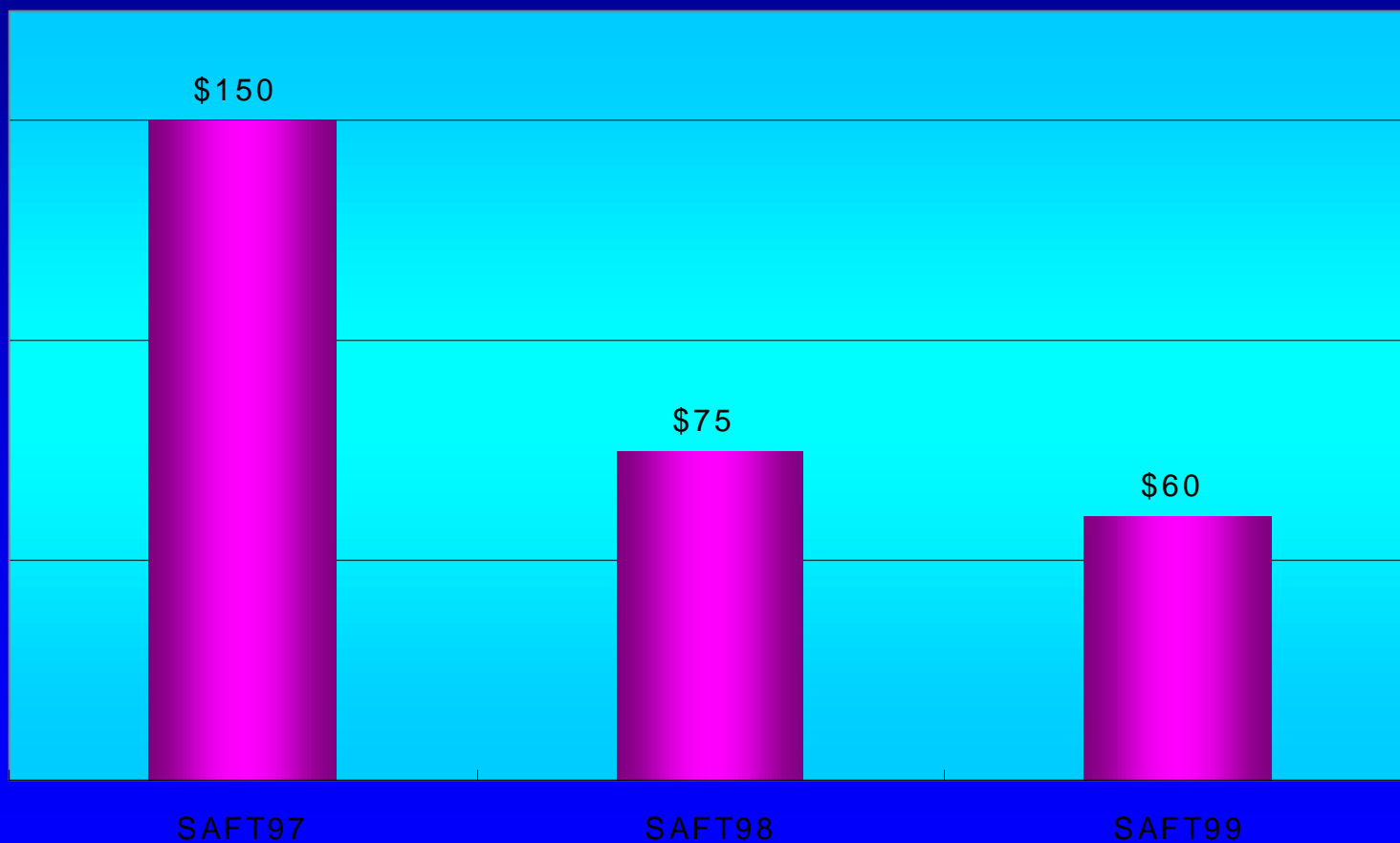
Flyback Transformer

HV Diode

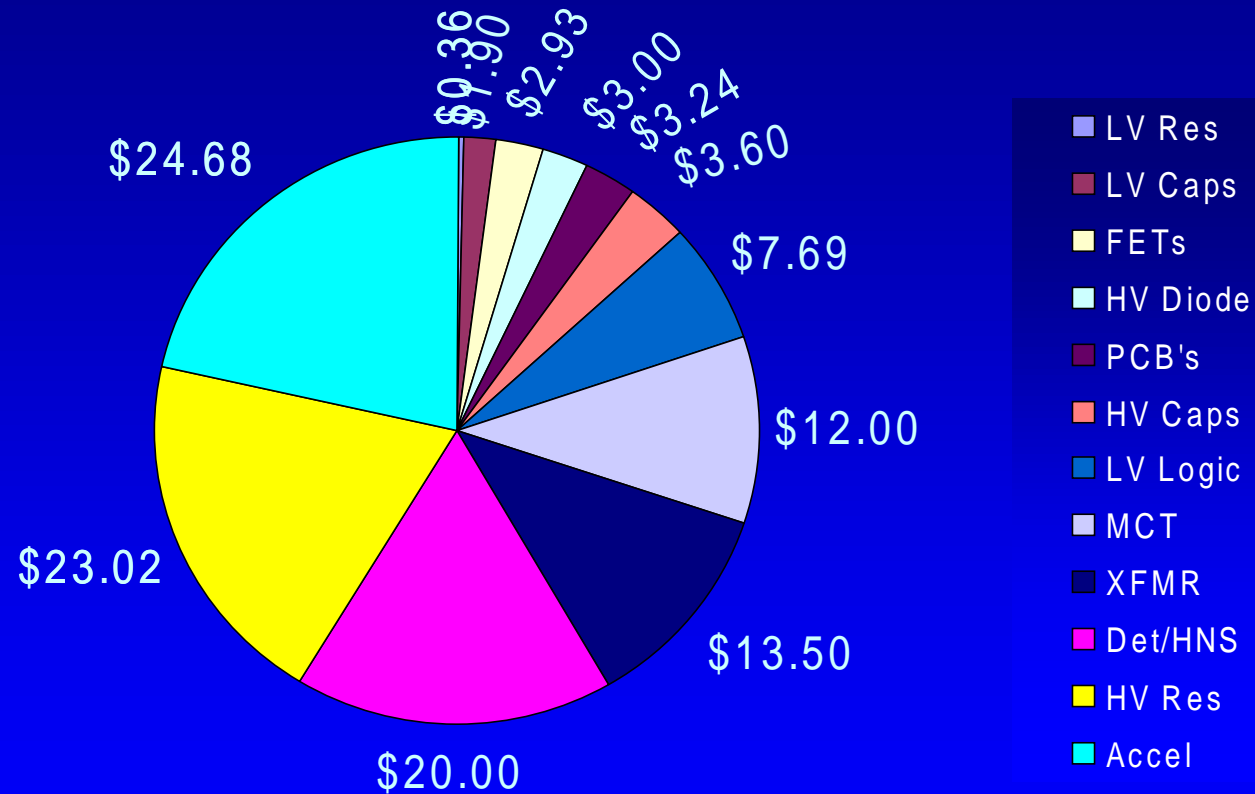




MATERIAL COST GOALS (1k Units)

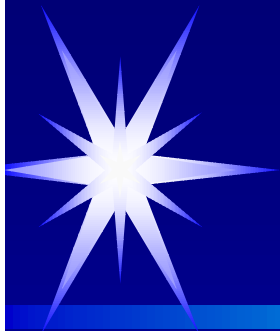


COMPONENT COST BREAKDOWN



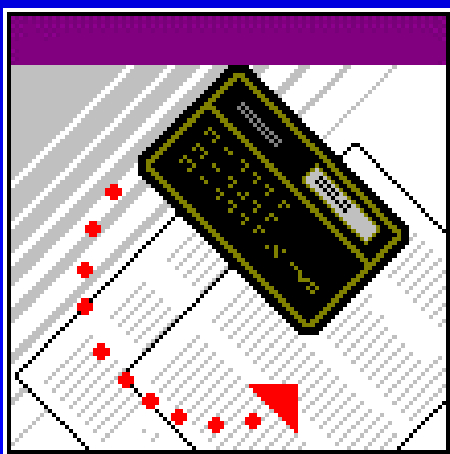
Total Component Cost = \$115.09

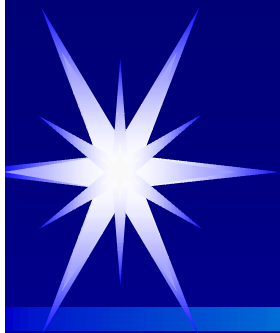




COMPONENT COST SUMMARY

➤ LV Parts	\$14.50	13%
➤ Accelerometer	\$24.68	21%
➤ DET & HNS	\$20.00	17%
➤ <u>HV Parts</u>	<u>\$56.74</u>	<u>49%</u>
➤ Total	\$115.92	100%



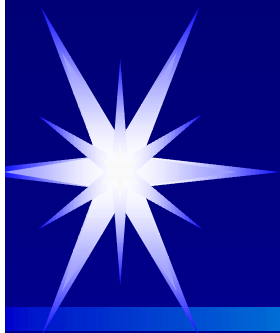


CURRENT TECHNOLOGY IMPROVEMENTS

* HV MCT Switch

- Improvements in switch gate design
 - Simplifies the required gate drive circuitry
- Improvements in packaging to better match ESAD applications
 - ✓ Two device packages will be available
 - ✓ Commercial TO-218 Package
 - ✓ Harris Thin Pack (half size for size 6 die)

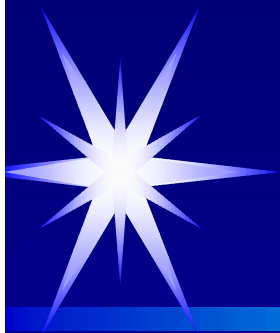




CURRENT TECHNOLOGY IMPROVEMENTS

- ✴ High Voltage Capacitor
 - Improvements in component internal design
 - Improved production yield
 - Increased component reliability
- Flyback Transformer
 - Improvements in component design and production techniques
 - Design modified and production techniques improved





FUTURE GOALS

- Implement a design using the current technology improvements
- Incorporate manufacturability improvements
- Define requirements for mortar and tank fuze applications

